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Practitioner's Docket No. U 13887-9

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PATENT
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Sung-Fei WANG, et al.
Serial No.: 10/087,432
Filed: March 1, 2002

For: **STACKED SEMICONDUCTOR CHIP PACKAGE**

**Assistant Commissioner for Patents
Washington, D.C. 20231**

Sir:

PRELIMINARY AMENDMENT

Please amend the above identified application as follows:

IN THE CLAIMS :

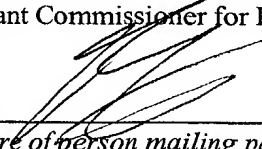
Please cancel claims 1-4:

Please add new claims 5-10

CERTIFICATE OF MAILING (37 CFR 1.8a)

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being deposited with the United States Postal Service on the date shown below with sufficient postage as first class mail in an envelope addressed to the: Assistant Commissioner for Patents, Washington, D.C. 20231

Date: April 24, 2002


(Signature of person mailing paper)

William R. Evans
(type or print name of person certifying)